

Appl. No. 10/709,428  
Amdt. dated December 21, 2005  
Reply to Office action of September 22, 2005

### **REMARKS/ARGUMENTS**

#### **1. Objection to the specification:**

The disclosure is objected to because of the following informalities: Applicant does not clearly describe a "first pin" and a "second pin" on the chip, and a "third bonding pad" connected to a second lead frame. The examiner suggests the use of consistent terminology throughout the disclosure and claims.

#### **Response:**

The claims have been amended to overcome this objection. The claims no longer recite first or second pins or first, second, or third bonding pads. All claimed limitations are now clearly disclosed in the specification and the figures, namely paragraphs 0021-0022 and Figure 6. Acceptance of the disclosure is respectfully requested.

#### **2. Objection to the claims:**

Claims 11, 19, 27, and 30 are objected to due to informalities.

#### **Response:**

Claims 11 and 19 have been amended to correct these informalities. The claims now recite that each bonding option unit contains a bonding pad and that each bonding pad has a corresponding first lead frame. Each bonding pad is connected to either the package substrate or the first lead frame for determining the voltage of the corresponding bonding option unit.

All claimed limitations are now clearly disclosed in the specification and the figures, namely paragraphs 0021-0022 and Figure 6. Acceptance of the amended claims is respectfully requested.

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3. Rejection of claims 11, 19, and 27-32 under 35 U.S.C. 102(b):

Claims 11, 19, and 27-32 are rejected under 35 U.S.C. 102(b) as being anticipated by Hara et al. (US 6,414,387, hereinafter Hara) for reasons of record.

**Response:**

Claims 11 and 19 have been amended to overcome this rejection. Claims 27-32 have been canceled, and are no longer in need of consideration. Claims 11 and 19 now recite that each bonding option unit contains a bonding pad and that each bonding pad has a corresponding first lead frame.

Each of the bonding pads is connected to either the package substrate or the first lead frame, which have logical opposite voltages, for determining the voltage of the corresponding bonding option unit. Therefore, claims 11 and 19 recite that each bonding pad has two bonding options.

On the other hand, Hara does not teach that each bonding pad has a corresponding first lead frame, and that the first lead frame has a voltage that is the logical opposite of the voltage of the package substrate. Moreover, Hara does not teach that each bonding pad can be selectively connected to the package substrate or its corresponding first lead frame.

Although Hara teaches in column 10, lines 40-49 that the bonding wires can be used for grounding, for power supply, or for carrying other signals, this teaching only applies to bonding wires 8 and 9 and their corresponding bonding pads 6, 5. This teaching does not apply to the other bonding pads 4, 7, 14, and 16 described in Hara's disclosure. Therefore, Hara fails to teach that each bonding pad has a corresponding first lead frame, and that the bonding pad can be selectively connected to the package substrate or the first lead frame. Reconsideration of claims 11 and 19 is therefore respectfully requested.

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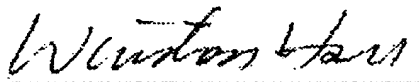
4. Introduction to new claims 33 and 34:

New claims 33 and 34 each recite that each bonding pad has a corresponding second lead frame that is used for inputting or outputting signals to the bonding pad. Each bonding pad is selectively connected to the package substrate, the corresponding first lead frame, or the corresponding second lead frame.

On the other hand, Hara does not teach or suggest that each of the bonding pads has corresponding first and second lead frames, and that each bonding pad can be selectively connected to the first lead frame, the second lead frame, or the package substrate. Acceptance of new claims 33 and 34 is respectfully requested.

In view of the claim amendments, the applicants submit that all pending claims are patentably distinguished from the cited prior art. The applicant therefore respectfully requests that a timely Notice of Allowance be issued in this case.

Sincerely yours,



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